IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Douglas D. Coolbaugh, et al.

Examiner: Unassigned

Serial No: 10/707,064

Art Unit: Unassigned

Filed: 11/19/2003

Docket: BUR920020119US1 (16763)

For: OPTIMUM PADSET FOR WIRE BONDING RF TECHNOLOGIES WITH HIGH-Q INDUCTORS

Dated: November 11, 2003

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.97 and 1.98, it is requested that the six (6) references, which are listed on the attached Form PTO-1449, be made of record in the above-identified case.

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, P. O. Box 1450, Alexandria, VA 22313-1450 on

Dated: 1/21/04

Maryam Luisi

Maryam Luisi

Applicants are submitting copies of the above-cited references.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. § 1.97(b), no statement or fee is required.

Respectfully submitted,

Leslie S. Szivos, Ph.D.
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LSS/sf
Enclosures PTO 1449
Six (6) references

Form PTO-1449 (REV. 7-80) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

LIST OF PRIOR ART CITED BY APPLICANT

(Use several sheets if necessary)

Atty. Docket N .	Serial No.
BUR920020119US1 (16763)	
Applicant Douglas D. Coolbaugh, et al	
Filing Date	**Group** Unassigned

U.S. PATENT DOCUMENTS

EXAMINER INITIAL*		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA						
	AB						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		JP5-047859A	2/26/1993	JAPAN				

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

		S.G. Bombardier, et al. (1997) "Aluminum-Tungsten-Aluminum Sandwich for Semiconductor Chip Wirebond Pad", IBM Technical Disclosure Bulletin, Vol. 40, No. 6, page 131;
		C.R. Fedorko, Jr., et al. (1984) "Packaging Substrate with Top Surface Metallurgy Adapted for Mixed Technology Device Bonding and Method", IBM Technical Disclosure Bulletin, Vol. 26, No. 12, page 6624;
		D. Chance, et al. (1993) "Thin Film Metallurgical Structure and Wire for Engineering Chance", IBM Technical Disclosure Bulletin, Vol. 36, No. 1, page 41;
		T.H. Chiles (1989) Abstract of Disclosure No. 30581 entitled "Use of a Composite Metal Pad for Wirebond connection to the Copper Core of a Metal Core Substrate Circuit Board" Kenneth Mason Publications, Ltd. England, No. 305 (1 page); and
		R. J. Bergeron, et al. (1992) Abstract of Disclosure No. 34237 entitled "Bond Pad Metallurgy for Wire Bonding", Kenneth Mason Publications, Ltd. England, No. 342 (1 page).

EXAMINER	DATE CONSIDERED

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.